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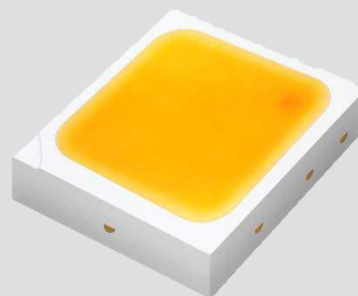
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Middle Power LED Series  
3030

LM302B  
CRI70



#### Features & Benefits

- Superior mid power LED with wide over-drive range up to 1.5W
- Mold resin for high reliability
- Standard form factor for design flexibility (3.0 × 3.0 mm)

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## 1. Characteristics

### a) Absolute Maximum Rating

Item	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	$T_a$	-40 ~ +85	°C	-
Storage Temperature	$T_{stg}$	-40 ~ +100	°C	-
LED Junction Temperature	$T_j$	125	°C	-
Forward Current	$I_F$	250	mA	-
Assembly Process Temperature	-	260 <10	°C s	-
ESD (HBM)	-	5	kV	-

**b) Electro-optical Characteristics ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )**

Item	Unit	Rank	Bin	Min.	Typ.	Max.
Forward Voltage ( $V_F$ )	V	YB	AY	5.4	-	5.6
			AZ	5.6	-	5.8
			A1	5.8	-	6.0
			A2	6.0	-	6.2
			A3	6.2	-	6.4
Reverse Voltage (@ 5 mA)	V			0.7	-	1.2
Color Rendering Index ( $R_a$ )	-			70	-	-
Special CRI (R9)	-			-	-	-
Thermal Resistance (junction to solder point)	$^\circ\text{C/W}$			-	8	-
Beam Angle	$^\circ$			-	115	-

**Note:**

Samsung maintains measurement tolerance of: forward voltage =  $\pm 0.1 \text{ V}$ , CRI =  $\pm 3$ , R9 =  $\pm 6.5$

**b) Electro-optical Characteristics ( $T_s = 85\text{ }^\circ\text{C}$ )**

Item	CRI	Nominal CCT (K)	SC		SD		SE		SF		SG		Current
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
			97	106	106	115	115	124	124	133	133	142	
Luminous Flux ( $\Phi_v$ )	70	3000											
		3500											
		4000											
		5000											

**Note:**

Samsung maintains measurement tolerance of: forward voltage =  $\pm 0.1\text{V}$ , luminous flux =  $\pm 5\%$ , CRI =  $\pm 3$ , R9 =  $\pm 6.5$

## 2. Product Code Information

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	P	M	W	H	T	3	2	9	F	D	3	Y	B	R	0	S	0

Digit	PKG Information	Code	Specification
1 2 3	Samsung Package Middle Power	SPM	
4 5	Color	WH	White
6	Product Version	T	
7 8 9	Form Factor	329	3.0 x 3.0 x 0.7 mm; 2 pads; 1chip;
10	Sorting Current (mA)	F	150 mA
11	Chromaticity Coordinates	D	ANSI Standard
12	CRI	3	Min. 70
13 14	Forward Voltage (V)	YB	5.4~6.4V
15 16	CCT (K)	V★ U★ T★ R★	3000 V1, V2, V3, V4, V5, V6, V7, V8, V9, VA, VB, VC, VD, VE, VF, VG 3500 U1, U2, U3, U4, U5, U6, U7, U8, U9, UA, UB, UC, UD, UE, UF, UG 4000 T1, T2, T3, T4, T5, T6, T7, T8, T9, TA, TB, TC, TD, TE, TF, TG 5000 R1, R2, R3, R4, R5, R6, R7, R8, R9, RA, RB, RC, RD, RE, RF, RG
			★ : Cool white: "0" (Whole bin) or "K" (Kitting bin)
17 18	Luminous Flux	S0	Bin Code: SD, SE, SF

a) Luminous Flux Bins ( $I_F = 150 \text{ mA}$ ,  $T_s = 85^\circ\text{C}$ )

CRI ( $R_a$ ) Min.	Nominal CCT (K)	Product Code	Flux Bin	Flux Range ( $\Phi_v$ , lm)
70	3000	SPMWHT329FD3YBV★S0	SD	106 ~ 115
			SE	115 ~ 124
	3500	SPMWHT329FD3YBU★S0	SD	106 ~ 115
			SE	115 ~ 124
	4000	SPMWHT329FD3YBT★S0	SE	115 ~ 124
			SF	124 ~ 133
	5000	SPMWHT329FD3YBR★S0	SE	115 ~ 124
			SF	124 ~ 133

**Note:**

"★" can be "0" (Whole bin) or "K" (Kitting bin) of the color binning

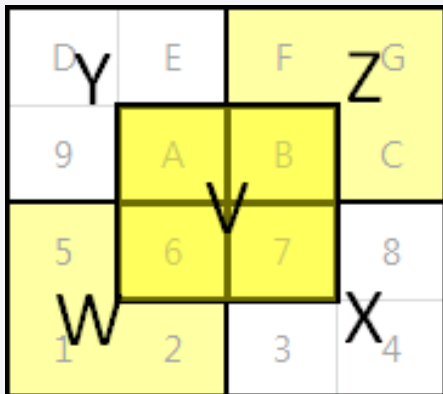


**b) Kitting rule**

**1) Kitting bin Concept**

1. Under agreement between customer and SAMSUNG ELECTRONICS, SAMSUNG can supply kitting bin (VF, Color, Im).
2. A forward voltage (VF) of kitting bin is combined by a pair of same VF rank such as (AY+AY), (AZ+AZ), (A1+A1), (A2+A2) or (A3+A3).
3. A Chromaticity Coordinates of kitting bin is mixed by kitting procedure.(below kitting simulation)

**[Kitting example]**



**[Binning Information]**

Item	Bin #1	Bin #2
VF	AY	AY
	AZ	AZ
	A1	A1
	A2	A2
	A3	A3
CIE	W (1, 2, 5, 6 bin)	Z (B, C, F, G bin)
	V (6, 7, A, B bin)	V (6, 7, A, B bin)
	X (3, 4, 7, 8 bin)	Y (9, A, D, E bin)
IV	SD	SD
	SE	SE
	SF	SF

※ Each of V,W,X,Y and Z can be one bin without details division.

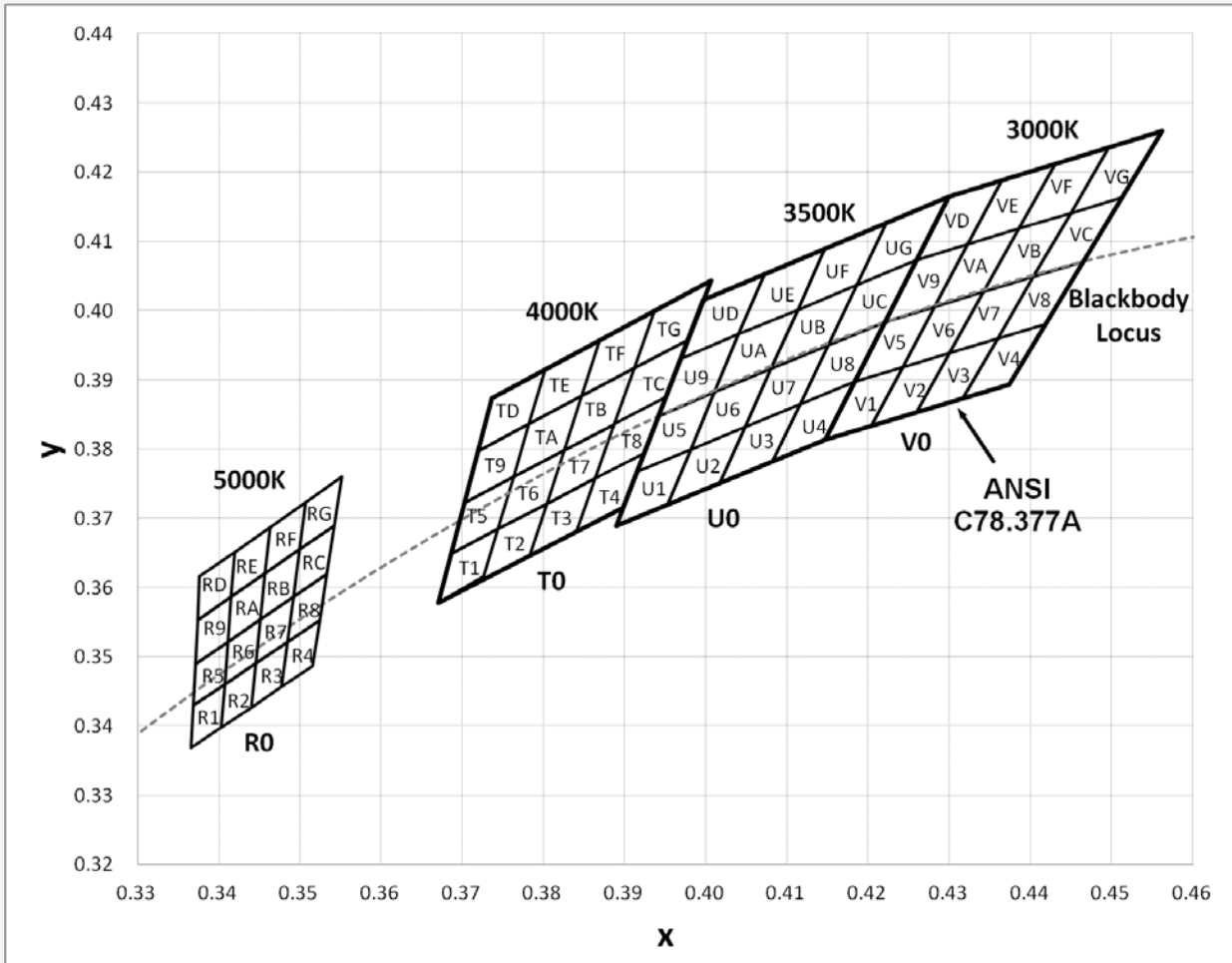
c) Color Bins ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ °C}$ )

CRI ( $R_a$ ) Min.	Nominal CCT (K)	Product Code	Color Rank	Chromaticity Bins
70	3000	SPMWHT329FD3YBV0S0	V0 (Whole bin)	V1, V2, V3, V4, V5, V6, V7, V8, V9, VA, VB, VC, VD, VE, VF, VG
		SPMWHT329FD3YBVK0S0	VK (Kitting bin)	VV, VW, VX, VY, VZ
	3500	SPMWHT329FD3YBU0S0	U0 (Whole bin)	U1, U2, U3, U4, U5, U6, U7, U8, U9, UA, UB, UC, UD, UE, UF, UG
		SPMWHT329FD3YBUK0S0	UK (Kitting bin)	UV, UW, UX, UY, UZ
	4000	SPMWHT329FD3YBT0S0	T0 (Whole bin)	T1, T2, T3, T4, T5, T6, T7, T8, T9, TA, TB, TC, TD, TE, TF, TG
		SPMWHT329FD3YBT0S0	TK (Kitting bin)	TV, TW, TX, TY, TZ
	5000	SPMWHT329FD3YBR0S0	R0 (Whole bin)	R1, R2, R3, R4, R5, R6, R7, R8, R9 RA, RB, RC, RD, RE, RF, RG
		SPMWHT329FD3YBRK0S0	RK (Kitting bin)	RV, RW, RX, RY, RZ

d) Voltage Bins ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ °C}$ )

CRI ( $R_a$ ) Min.	Nominal CCT (K)	Product Code	Voltage Rank	Voltage Bin	Voltage Range (V)
-	-	-	YB	AY	5.4 ~ 5.6
-	-	-		AZ	5.6 ~ 5.8
-	-	-		A1	5.8 ~ 6.0
-	-	-		A2	6.0 ~ 6.2
-	-	-		A3	6.2 ~ 6.4
-	-	-			

e) Chromaticity Region & Coordinates ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )



e) Chromaticity Region & Coordinates

Region	CIE x	CIE y	Region	CIE x	CIE y
<b>V rank (3000 K)</b>					
V1	0.4147	0.3814	V9	0.4221	0.3984
	0.4183	0.3898		0.4259	0.4073
	0.4242	0.3919		0.4322	0.4096
	0.4203	0.3833		0.4281	0.4006
V2	0.4203	0.3833	VA	0.4281	0.4006
	0.4242	0.3919		0.4322	0.4096
	0.4300	0.3939		0.4385	0.4119
	0.4259	0.3853		0.4342	0.4028
V3	0.4259	0.3853	VB	0.4342	0.4028
	0.4300	0.3939		0.4385	0.4119
	0.4359	0.3960		0.4449	0.4141
	0.4316	0.3873		0.4403	0.4049
V4	0.4316	0.3873	VC	0.4403	0.4049
	0.4359	0.3960		0.4449	0.4141
	0.4418	0.3981		0.4513	0.4164
	0.4373	0.3893		0.4465	0.4071
V5	0.4183	0.3898	VD	0.4259	0.4073
	0.4221	0.3984		0.4299	0.4165
	0.4281	0.4006		0.4364	0.4188
	0.4242	0.3919		0.4322	0.4096
V6	0.4242	0.3919	VE	0.4322	0.4096
	0.4281	0.4006		0.4364	0.4188
	0.4342	0.4028		0.4430	0.4212
	0.4300	0.3939		0.4385	0.4119
V7	0.4300	0.3939	VF	0.4385	0.4119
	0.4342	0.4028		0.4430	0.4212
	0.4403	0.4049		0.4496	0.4236
	0.4359	0.3960		0.4449	0.4141
V8	0.4359	0.3960	VG	0.4449	0.4141
	0.4403	0.4049		0.4496	0.4236
	0.4465	0.4071		0.4562	0.4260
	0.4418	0.3981		0.4513	0.4164

Region	CIE x	CIE y	Region	CIE x	CIE y
<b>U rank (3500 K)</b>					
U1	0.3889	0.3690	U9	0.3941	0.3848
	0.3915	0.3768		0.3968	0.3930
	0.3981	0.3800		0.4040	0.3966
	0.3953	0.3720		0.4010	0.3882
U2	0.3953	0.3720	UA	0.4010	0.3882
	0.3981	0.3800		0.4040	0.3966
	0.4048	0.3832		0.4113	0.4001
	0.4017	0.3751		0.4080	0.3916
U3	0.4017	0.3751	UB	0.4080	0.3916
	0.4048	0.3832		0.4113	0.4001
	0.4116	0.3865		0.4186	0.4037
	0.4082	0.3782		0.4150	0.3950
U4	0.4082	0.3782	UC	0.4150	0.3950
	0.4116	0.3865		0.4186	0.4037
	0.4183	0.3898		0.4259	0.4073
	0.4147	0.3814		0.4221	0.3984
U5	0.3915	0.3768	UD	0.3968	0.3930
	0.3941	0.3848		0.3996	0.4015
	0.4010	0.3882		0.4071	0.4052
	0.3981	0.3800		0.4040	0.3966
U6	0.3981	0.3800	UE	0.4040	0.3966
	0.4010	0.3882		0.4071	0.4052
	0.4080	0.3916		0.4146	0.4089
	0.4048	0.3832		0.4113	0.4001
U7	0.4048	0.3832	UF	0.4113	0.4001
	0.4080	0.3916		0.4146	0.4089
	0.4150	0.3950		0.4222	0.4127
	0.4116	0.3865		0.4186	0.4037
U8	0.4116	0.3865	UG	0.4186	0.4037
	0.4150	0.3950		0.4222	0.4127
	0.4221	0.3984		0.4299	0.4165
	0.4183	0.3898		0.4259	0.4073

**Note:** Samsung maintains measurement tolerance of:  
Cx, Cy = ±0.005

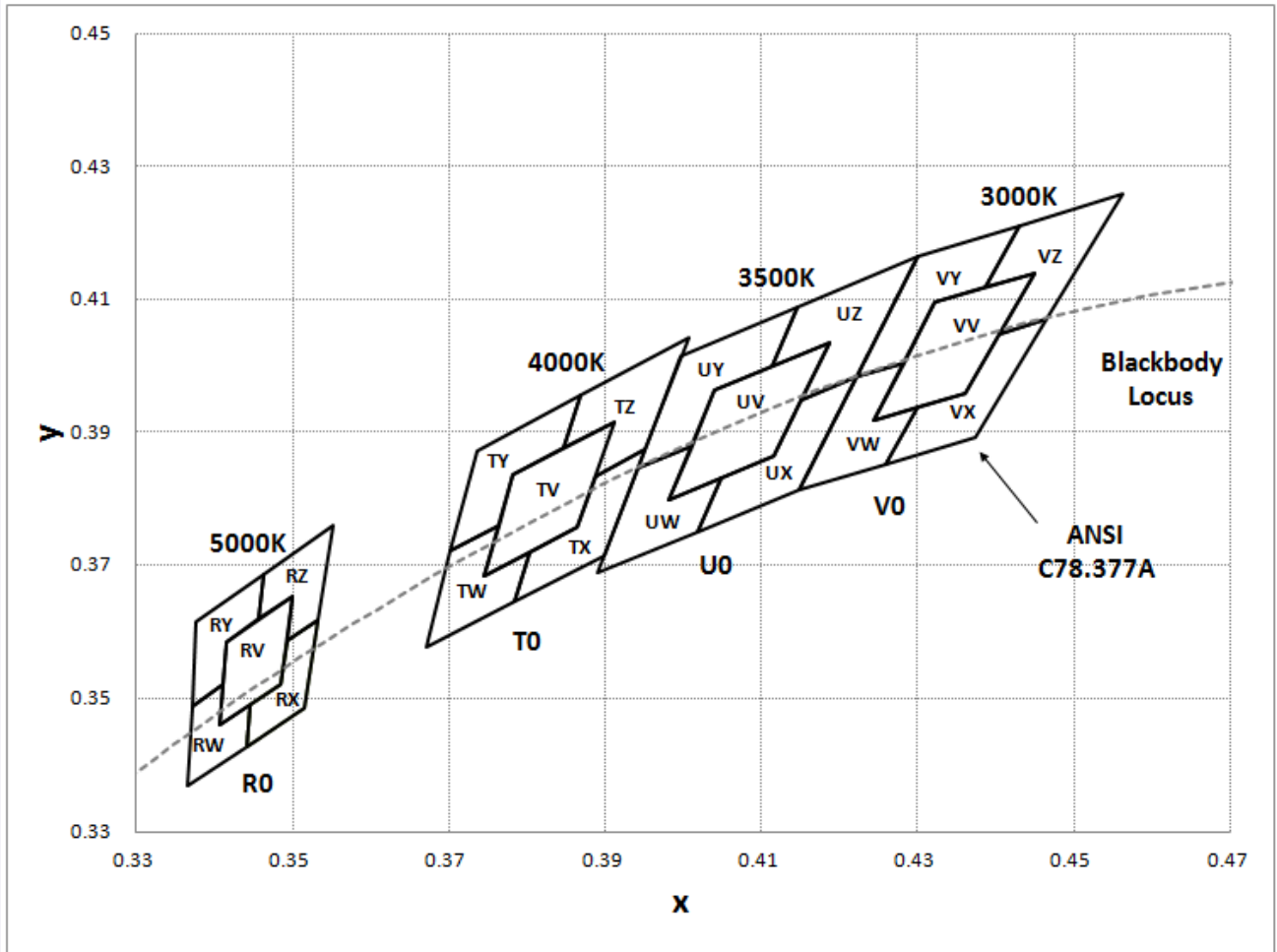


## e) Chromaticity Region &amp; Coordinates

Region	CIE x	CIE y	Region	CIE x	CIE y
<b>T rank (4000 K)</b>					
T1	0.3670	0.3578	T9	0.3702	0.3722
	0.3726	0.3612		0.3763	0.3760
	0.3744	0.3685		0.3782	0.3837
	0.3686	0.3649		0.3719	0.3797
T2	0.3726	0.3612	TA	0.3763	0.3760
	0.3783	0.3646		0.3825	0.3798
	0.3804	0.3721		0.3847	0.3877
	0.3744	0.3685		0.3782	0.3837
T3	0.3783	0.3646	TB	0.3825	0.3798
	0.3840	0.3681		0.3887	0.3836
	0.3863	0.3758		0.3912	0.3917
	0.3804	0.3721		0.3847	0.3877
T4	0.3840	0.3681	TC	0.3887	0.3837
	0.3898	0.3716		0.3950	0.3875
	0.3924	0.3794		0.3978	0.3958
	0.3863	0.3758		0.3912	0.3917
T5	0.3686	0.3649	TD	0.3719	0.3797
	0.3744	0.3685		0.3782	0.3837
	0.3763	0.3760		0.3802	0.3916
	0.3702	0.3722		0.3736	0.3874
T6	0.3744	0.3685	TE	0.3782	0.3837
	0.3804	0.3721		0.3847	0.3877
	0.3825	0.3798		0.3869	0.3958
	0.3763	0.376		0.3802	0.3916
T7	0.3804	0.3721	TF	0.3847	0.3877
	0.3863	0.3758		0.3912	0.3917
	0.3887	0.3836		0.3937	0.4001
	0.3825	0.3798		0.3869	0.3958
T8	0.3863	0.3758	TG	0.3912	0.3917
	0.3924	0.3794		0.3978	0.3958
	0.3950	0.3875		0.4006	0.4044
	0.3887	0.3836		0.3937	0.4001

**Note:** Samsung maintains measurement tolerance of:  
Cx, Cy = ±0.005

Region	CIE x	CIE y	Region	CIE x	CIE y
<b>R rank (5000 K)</b>					
R1	0.3366	0.3369	R9	0.3371	0.3490
	0.3369	0.3430		0.3374	0.3553
	0.3407	0.3460		0.3415	0.3587
	0.3403	0.3398		0.3411	0.3522
R2	0.3403	0.3398	RA	0.3411	0.3522
	0.3407	0.3460		0.3415	0.3587
	0.3446	0.3491		0.3457	0.3621
	0.3440	0.3427		0.3451	0.3554
R3	0.3440	0.3427	RB	0.3451	0.3554
	0.3446	0.3491		0.3457	0.3621
	0.3485	0.3522		0.3500	0.3655
	0.3478	0.3457		0.3492	0.3587
R4	0.3478	0.3457	RC	0.3492	0.3587
	0.3485	0.3522		0.3500	0.3655
	0.3524	0.3554		0.3542	0.3690
	0.3515	0.3487		0.3533	0.3620
R5	0.3369	0.3430	RD	0.3374	0.3553
	0.3371	0.3490		0.3376	0.3616
	0.3411	0.3522		0.3420	0.3652
	0.3407	0.3460		0.3415	0.3587
R6	0.3407	0.3460	RE	0.3415	0.3587
	0.3411	0.3522		0.3420	0.3652
	0.3451	0.3554		0.3463	0.3687
	0.3446	0.3491		0.3457	0.3621
R7	0.3446	0.3491	RF	0.3457	0.3621
	0.3451	0.3554		0.3463	0.3687
	0.3492	0.3587		0.3507	0.3724
	0.3485	0.3522		0.3500	0.3655
R8	0.3485	0.3522	RG	0.3500	0.3655
	0.3492	0.3587		0.3507	0.3724
	0.3533	0.3620		0.3551	0.3760
	0.3524	0.3554		0.3542	0.3690

f) Kitting Chromaticity Region & Coordinates ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )

**f) Kitting Chromaticity Region & Coordinates ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )**

Region	CIE x	CIE y	Region	CIE x	CIE y
<b>V rank (3000 K)</b>					
VV	0.4242	0.3919			
	0.4359	0.3960			
	0.4449	0.4141			
	0.4322	0.4096			
VW	0.4147	0.3814	VY	0.4221	0.3984
	0.4259	0.3853		0.4281	0.4006
	0.4300	0.3939		0.4322	0.4096
	0.4242	0.3919		0.4385	0.4119
	0.4281	0.4006		0.4430	0.4212
	0.4221	0.3984		0.4299	0.4165
VX	0.4259	0.3853	VZ	0.4403	0.4049
	0.4373	0.3893		0.4465	0.4071
	0.4465	0.4071		0.4562	0.4260
	0.4403	0.4049		0.4430	0.4212
	0.4359	0.3960		0.4385	0.4119
	0.4300	0.3939		0.4449	0.4141

Region	CIE x	CIE y	Region	CIE x	CIE y
<b>U rank (3500 K)</b>					
UV	0.3981	0.3800			
	0.4116	0.3865			
	0.4186	0.4037			
	0.4040	0.3966			
UW	0.3889	0.3690	UY	0.3941	0.3848
	0.4017	0.3751		0.4010	0.3882
	0.4048	0.3832		0.4040	0.3966
	0.3981	0.3800		0.4113	0.4001
	0.4010	0.3882		0.4146	0.4089
	0.3941	0.3848		0.3996	0.4015
UX	0.4017	0.3751	UZ	0.4150	0.3950
	0.4147	0.3814		0.4221	0.3984
	0.4221	0.3984		0.4299	0.4165
	0.4150	0.3950		0.4146	0.4089
	0.4116	0.3865		0.4113	0.4001
	0.4048	0.3832		0.4186	0.4037

**Note:** Samsung maintains measurement tolerance of:  
 $C_x, C_y = \pm 0.005$



## f) Kitting Chromaticity Region &amp; Coordinates

Region	CIE x	CIE y	Region	CIE x	CIE y
<b>T rank (4000 K)</b>					
TV	0.3744	0.3685			
	0.3863	0.3758			
	0.3912	0.3917			
	0.3782	0.3837			
TW	0.3670	0.3578	TY	0.3702	0.3722
	0.3783	0.3646		0.3763	0.3760
	0.3804	0.3721		0.3782	0.3837
	0.3744	0.3685		0.3847	0.3877
	0.3763	0.3760		0.3869	0.3958
	0.3702	0.3722		0.3736	0.3874
TX	0.3783	0.3646	TZ	0.3887	0.3837
	0.3898	0.3716		0.3950	0.3875
	0.3950	0.3875		0.4006	0.4044
	0.3887	0.3837		0.3869	0.3958
	0.3863	0.3758		0.3847	0.3877
	0.3804	0.3721		0.3912	0.3917

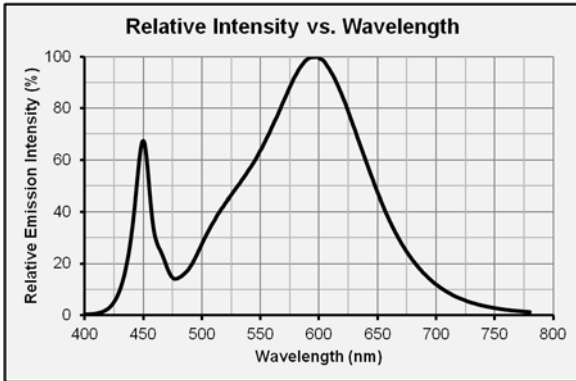
Region	CIE x	CIE y	Region	CIE x	CIE y
<b>R rank (5000 K)</b>					
RV	0.3407	0.3460			
	0.3485	0.3524			
	0.3500	0.3655			
	0.3415	0.3588			
RW	0.3366	0.3369	RY	0.3371	0.3493
	0.3440	0.3427		0.3411	0.3525
	0.3446	0.3491		0.3415	0.3588
	0.3407	0.3460		0.3457	0.3621
	0.3411	0.3525		0.3463	0.3687
	0.3371	0.3493		0.3376	0.3616
RX	0.3440	0.3428	RZ	0.3492	0.3587
	0.3514	0.3487		0.3553	0.3620
	0.3533	0.3620		0.3551	0.3760
	0.3492	0.3587		0.3463	0.3687
	0.3485	0.3522		0.3457	0.3621
	0.3446	0.3493		0.3500	0.3655

**Note:** Samsung maintains measurement tolerance of:  
Cx, Cy =  $\pm 0.005$

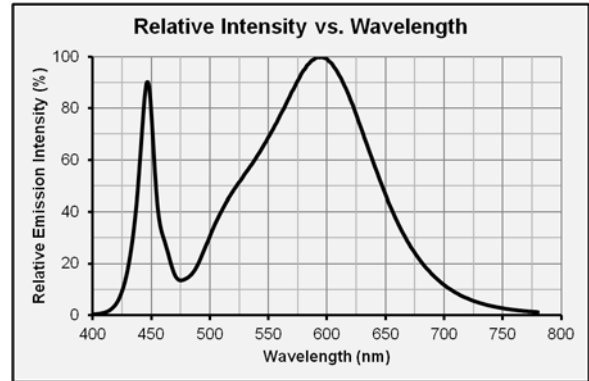
### 3. Typical Characteristics Graphs

#### a) Spectrum Distribution ( $I_f = 150 \text{ mA}$ , $T_s = 85 \text{ }^\circ\text{C}$ )

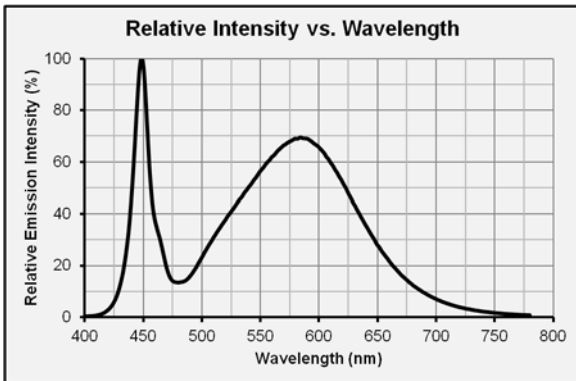
CCT: 3000K (70 CRI)



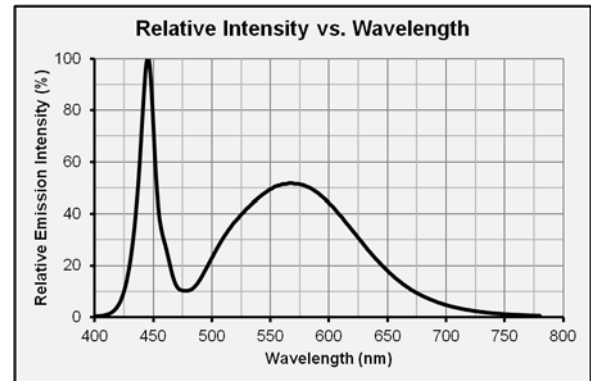
CCT: 3500K (70 CRI)



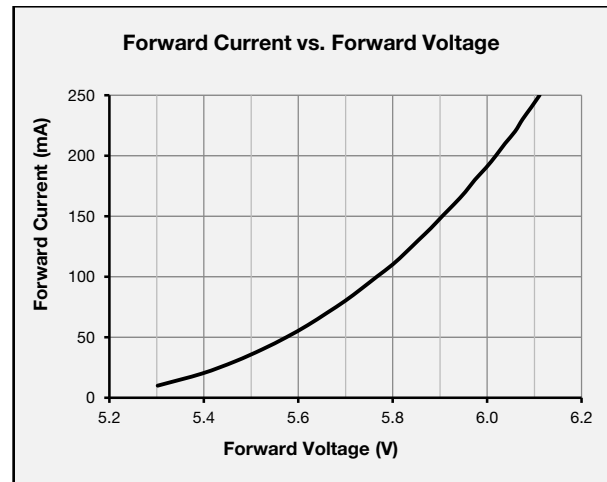
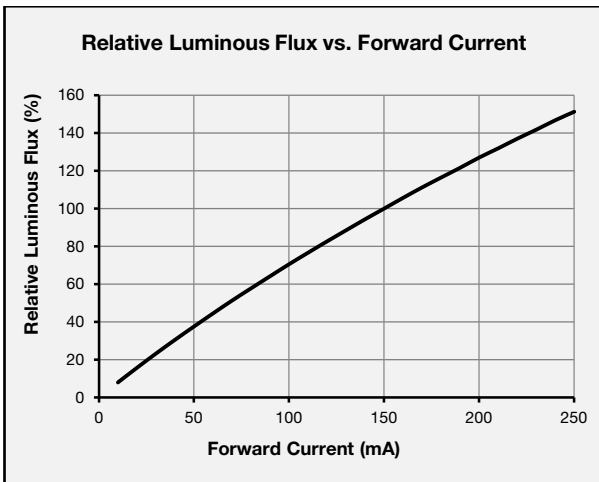
CCT: 4000K (70 CRI)



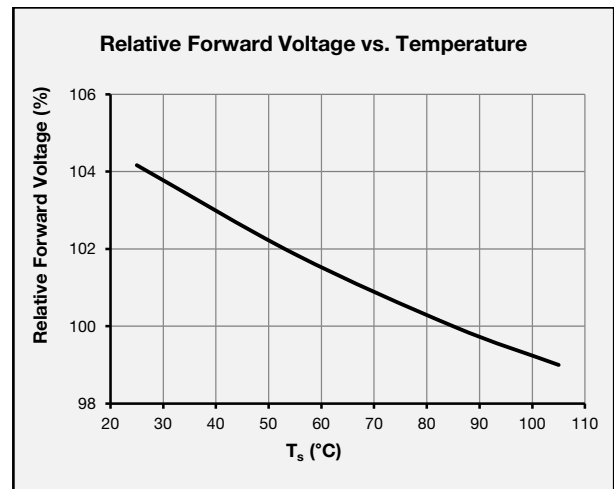
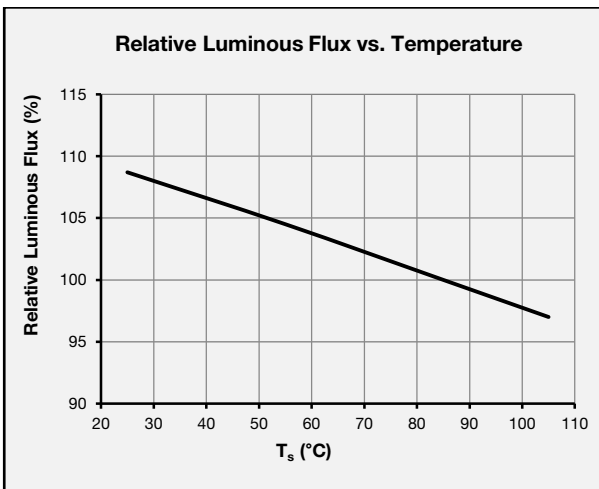
CCT: 5000K (70 CRI)



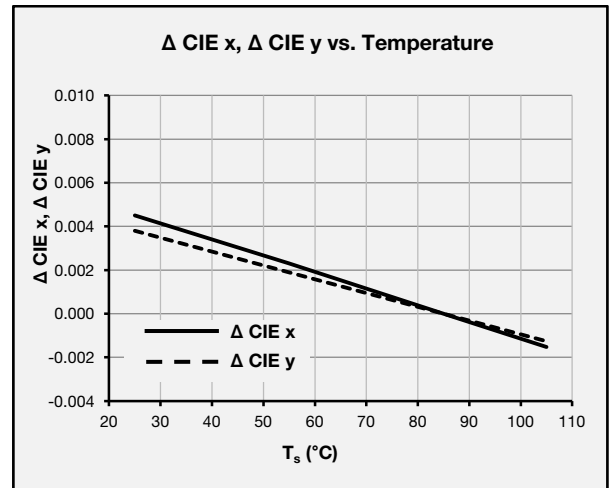
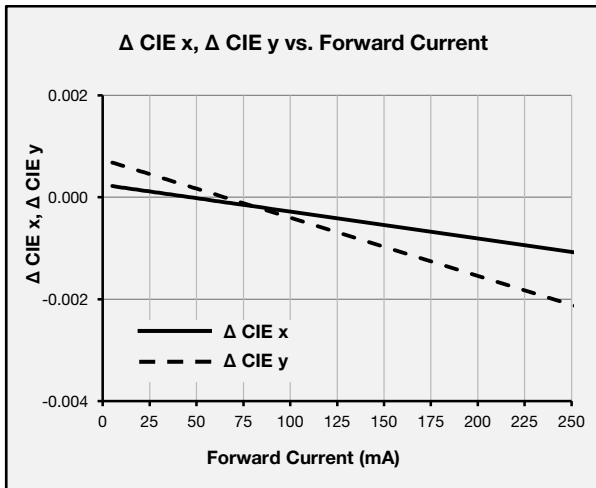
b) Forward Current Characteristics ( $T_s = 85\text{ }^\circ\text{C}$ )



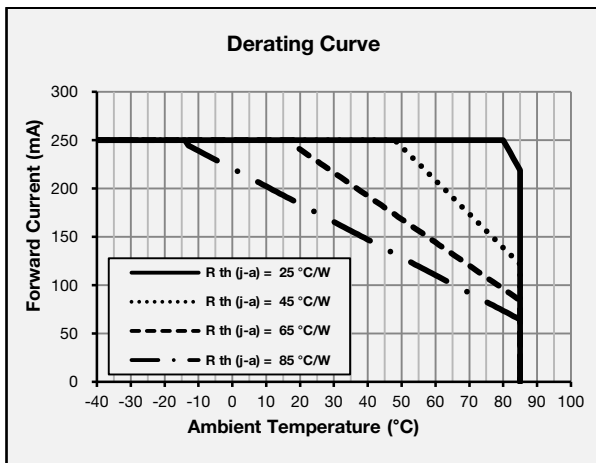
c) Temperature Characteristics ( $I_F = 150\text{ mA}$ )



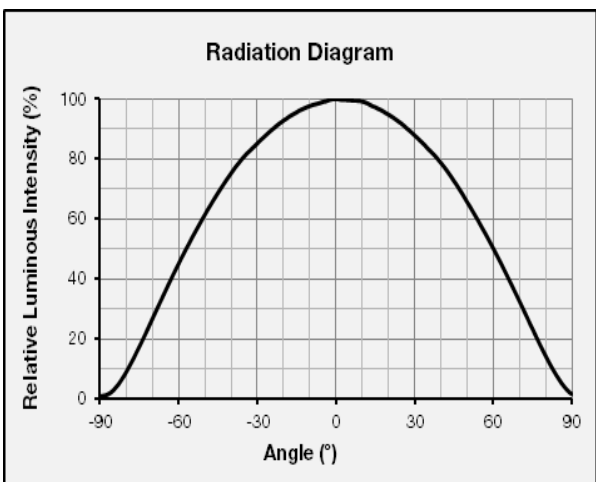
**d) Color Shift Characteristics ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )**



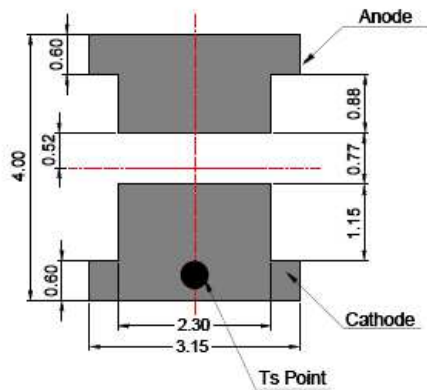
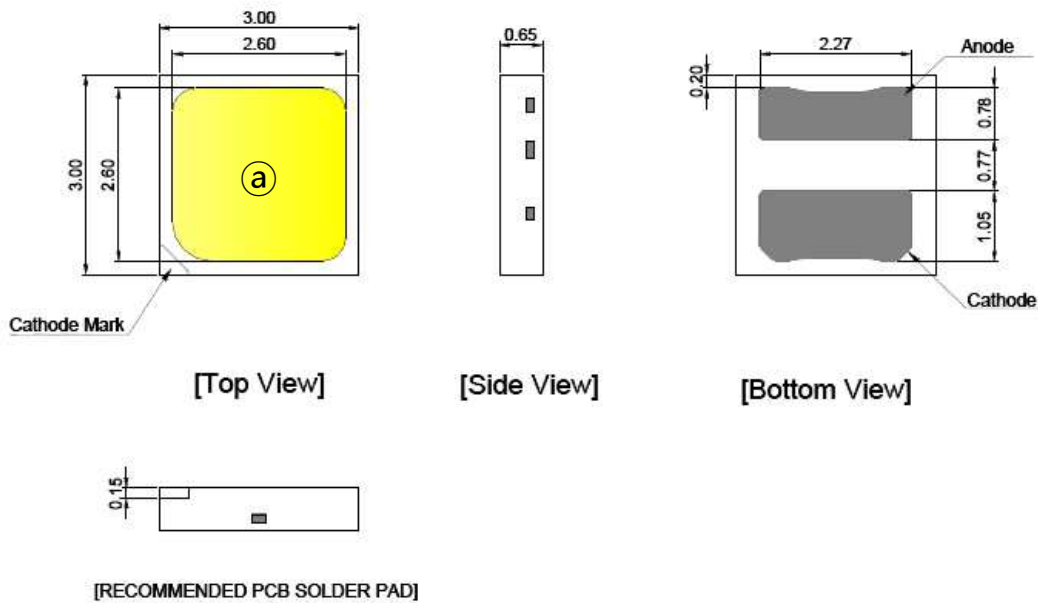
**e) Derating Curve**



**f) Beam Angle Characteristics ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )**



## 4. Outline Drawing & Dimension



- Measurement unit: mm
- Tolerance :  $\pm 0.1\text{mm}$
- Do not place pressure on the encapsulation resin ㊸

### Notes:

- 1) This LED has built-in ESD protection device(s) connected in parallel to LED chip(s).
- 2)  $T_s$  point and measurement method:
  - ① Measure one point at the cathode pad, if necessary remove PSR of PCB to reach  $T_s$  point.
  - ② All pads must be soldered to the PCB to dissipate heat properly, otherwise the LED can be damaged.

### Precautions:

- 1) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
- 2) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED's characteristics should be carefully checked before and after such repair.
- 3) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

## 5. Reliability Test Items & Conditions

### a) Test Items

Test Item	Test Condition	Test Hour / Cycle	Sample No.	
Room Temperature Life Test	25 °C, DC 250 mA	1000 h	22	
High Temperature Life Test	85 °C, DC 250 mA	1000 h	22	
High Temperature Humidity Life Test	85 °C, 85 % RH, DC 250 mA	1000 h	22	
Low Temperature Life Test	-40 °C, DC 250 mA	1000 h	22	
Powered Temperature Cycle Test	-45 °C ~ 85 °C, each 20 min, on/off 5 min Temp. Change time 100min, DC 250 mA	100 cycles	22	
Temperature Cycling	-45 °C / 15 min ↔ 125 °C / 15 min	500 cycles	100	
High Temperature Storage	120 °C	1000 h	11	
Low Temperature Storage	-40 °C	1000 h	11	
ESD (HBM)		R <sub>1</sub> : 10 MΩ R <sub>2</sub> : 1.5 kΩ	5 times	30
ESD (MM)		R <sub>1</sub> : 10 MΩ R <sub>2</sub> : 0 C: 200 pF V: ±0.5 kV	5 times	30
Vibration Test	20~2000~20 Hz, 200 m/s <sup>2</sup> , sweep 4 min X, Y, Z 3 direction, each 1 cycle	4 cycles	11	
Mechanical Shock Test	1500 g, 0.5 ms 3 shocks each X-Y-Z axis	5 cycles	11	

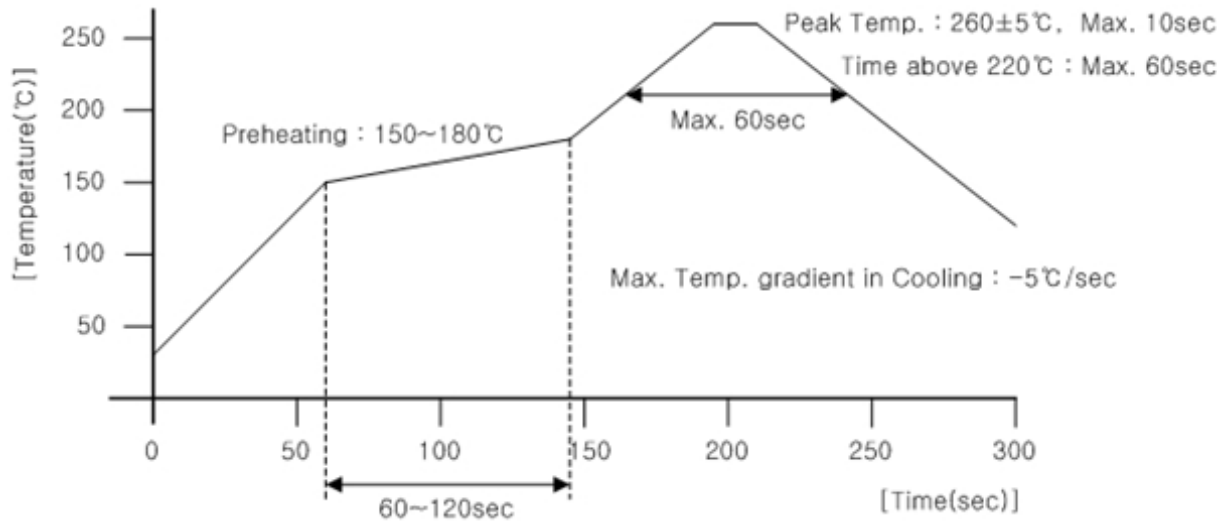
### b) Criteria for Judging the Damage

Item	Symbol	Test Condition (T <sub>s</sub> = 25 °C)	Limit	
			Min	Max
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 250 mA	Init. Value * 0.9	Init. Value * 1.1
Luminous Flux	Φ <sub>v</sub>	I <sub>F</sub> = 250 mA	Init. Value * 0.7	Init. Value * 1.1

## 6. Soldering Conditions

### a) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.



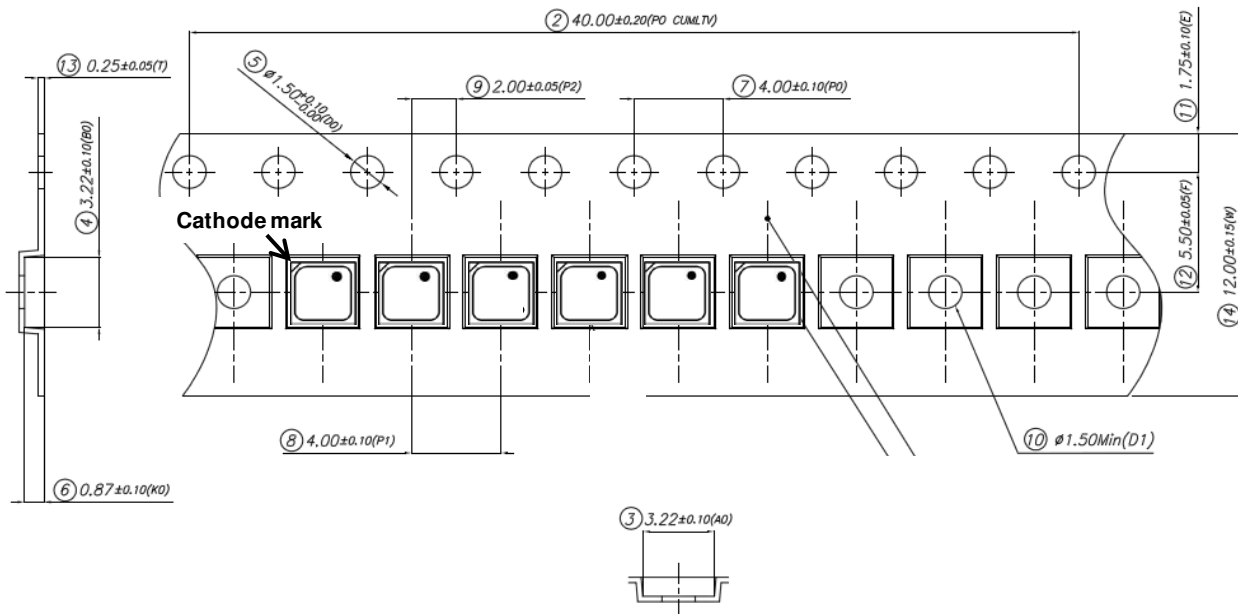
### b) Manual Soldering Conditions

Not more than 5 seconds @ max. 300 °C, under soldering iron.

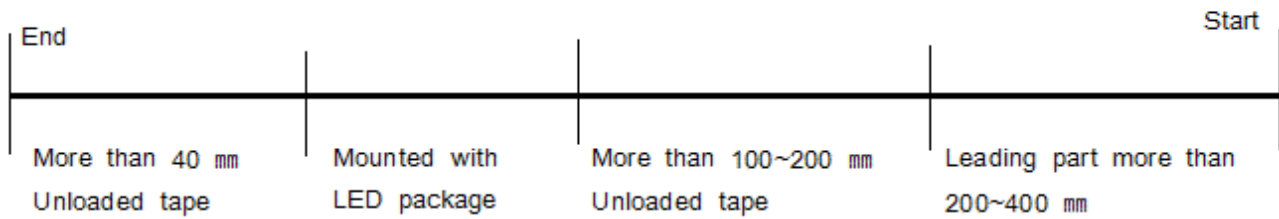
## 7. Tape & Reel

### a) Taping Dimension

(unit: mm)

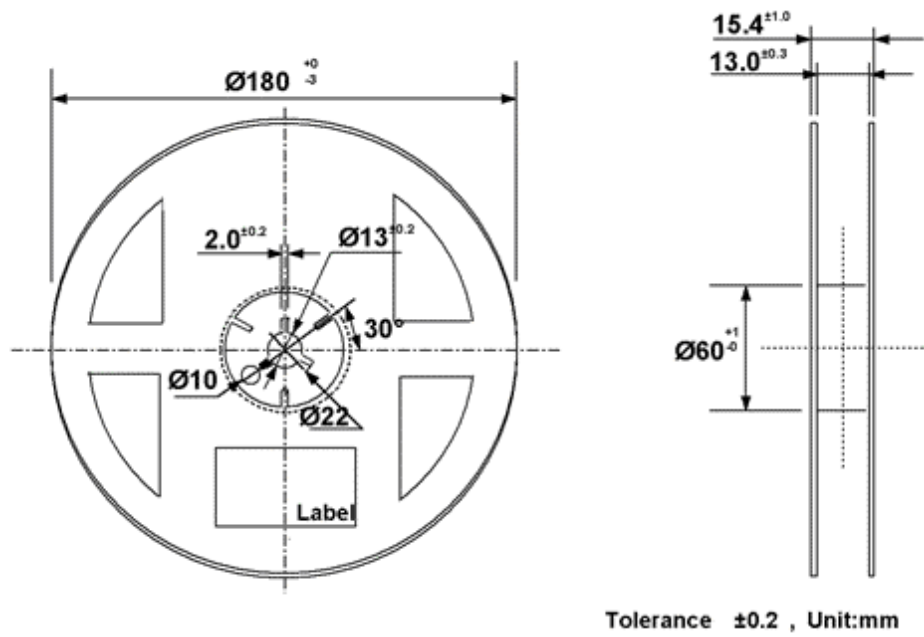


← Taping Direction





## b) Reel Dimension

**Notes:**

- 1) Quantity: The quantity/reel is 4,000 pcs
- 2) Cumulative tolerance: Cumulative tolerance / 10 pitches is  $\pm 0.2$  mm
- 3) Adhesion strength of cover tape: Adhesion strength is 0.1-0.7 N when the cover tape is turned off from the carrier tape at  $10^\circ$  angle to the carrier tape
- 4) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag

## 8. Label Structure

### a) Label Structure

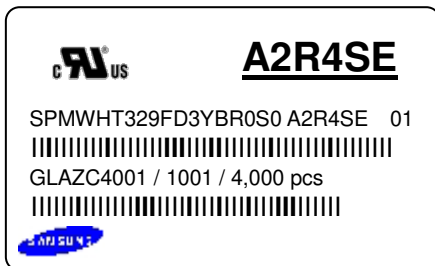


Note: Denoted bin code and product code above is only an example  
'★' means all kind of Chromaticity Coordinate Ranks

Bin Code:

- ①②: Forward Voltage bin (refer to page 9)
- ③④: Chromaticity bin (refer to page 11~14)
- ⑤⑥: Luminous Flux bin (refer to page 7)

### b) Lot Number



The lot number is composed of the following characters:

①②③④⑤⑥⑦⑧⑨ / 1①②③ / 4,000 pcs

- ① : Production site (S: Giheung, Korea, G: Tianjin, China)
- ② : L (LED)
- ③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)
- ④ : Year (Z: 2015, A: 2016, B:2017 ...)
- ⑤ : Month (1~9, A, B, C)
- ⑥ : Day (1~9, A, B~V)
- ⑦⑧⑨ : Product serial number (001 ~ 999)
- ①②③ : Reel number (001 ~ 999)